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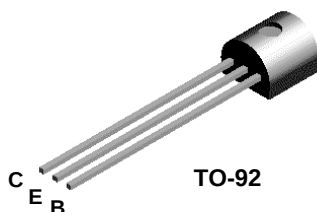
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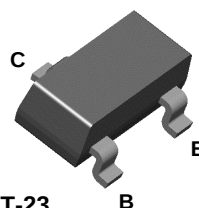
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MPSH10



TO-92

MMBTH10



SOT-23
Mark: 3E

NPN RF Transistor

This device is designed for use in low noise UHF/VHF amplifiers, with collector currents in the 100 μ A to 20 mA range in common emitter or common base mode of operations, and in low frequency drift, high output UHF oscillators. Sourced from Process 42.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	25	V
V _{CBO}	Collector-Base Voltage	30	V
V _{EBO}	Emitter-Base Voltage	3.0	V
I _C	Collector Current - Continuous	50	mA
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		MPSH10	*MMBTH10	
P _D	Total Device Dissipation Derate above 25°C	350 2.8	225 1.8	mW mW/°C
R _{θJC}	Thermal Resistance, Junction to Case	125		°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	357	556	°C/W

*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

NPN RF Transistor
(continued)

Electrical Characteristics TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHARACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Sustaining Voltage*	$I_C = 1.0\text{ mA}, I_B = 0$	25		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 100\text{ }\mu\text{A}, I_E = 0$	30		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10\text{ }\mu\text{A}, I_C = 0$	3.0		V
I_{CBO}	Collector Cutoff Current	$V_{CB} = 25\text{ V}, I_E = 0$		100	nA
I_{EBO}	Emitter Cutoff Current	$V_{EB} = 2.0\text{ V}, I_C = 0$		100	nA

ON CHARACTERISTICS

h_{FE}	DC Current Gain	$I_C = 4.0\text{ mA}, V_{CE} = 10\text{ V}$	60		
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 4.0\text{ mA}, I_B = 0.4\text{ mA}$		0.5	V
$V_{BE(on)}$	Base-Emitter On Voltage	$I_C = 4.0\text{ mA}, V_{CE} = 10\text{ V}$		0.95	V

SMALL SIGNAL CHARACTERISTICS

f_T	Current Gain - Bandwidth Product	$I_C = 4.0\text{ mA}, V_{CE} = 10\text{ V}, f = 100\text{ MHz}$	650		MHz
C_{cb}	Collector-Base Capacitance	$V_{CB} = 10\text{ V}, I_E = 0, f = 1.0\text{ MHz}$		0.7	pF
C_{fb}	Common-Base Feedback Capacitance	$V_{CB} = 10\text{ V}, I_E = 0, f = 1.0\text{ MHz}$	0.35	0.65	pF
$\tau_b \cdot C_c$	Collector Base Time Constant	$I_C = 4.0\text{ mA}, V_{CB} = 10\text{ V}, f = 31.8\text{ MHz}$		9.0	pS

*Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$

Spice Model

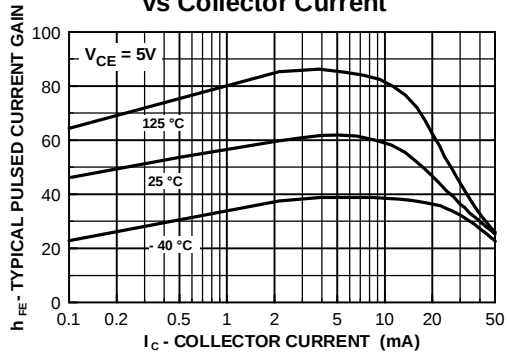
NPN (Is=69.28E-18 Xti=3 Eg=1.11 Vaf=100 Bf=308.6 Ne=1.197 Ise=69.28E-18 Ikf=22.83m Xtb=1.5 Br=1.11 Nc=2 Isc=0 Ikr=0 Rc=4 Cjc=1.042p Mjc=.2468 Vjc=.75 Fc=.5 Cje=1.52p Mje=.3223 Vje=.75 Tr=1.558n Tf=135.8p Itf=.27 Vtf=10 Xtf=30 Rb=10)

NPN RF Transistor (continued)

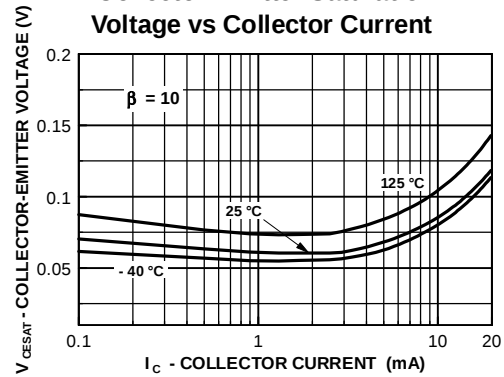
MPSSH10 / MMBTH10

Typical Characteristics

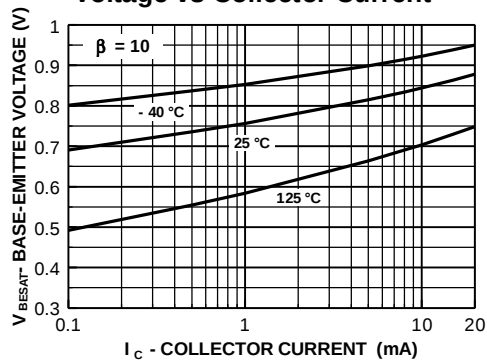
Typical Pulsed Current Gain
vs Collector Current



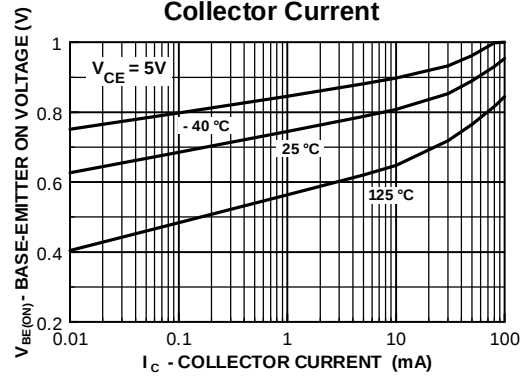
Collector-Emitter Saturation
Voltage vs Collector Current



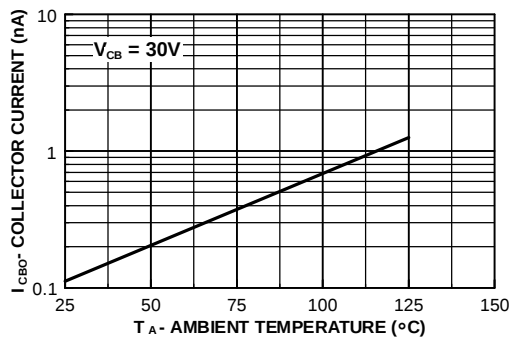
Base-Emitter Saturation
Voltage vs Collector Current



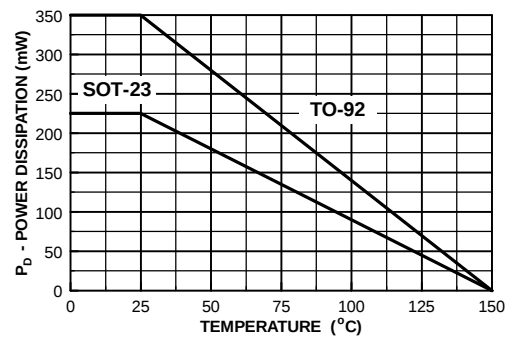
Base-Emitter ON Voltage vs
Collector Current



Collector-Cutoff Current
vs Ambient Temperature

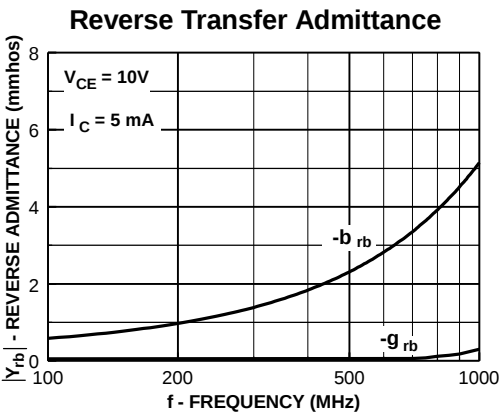
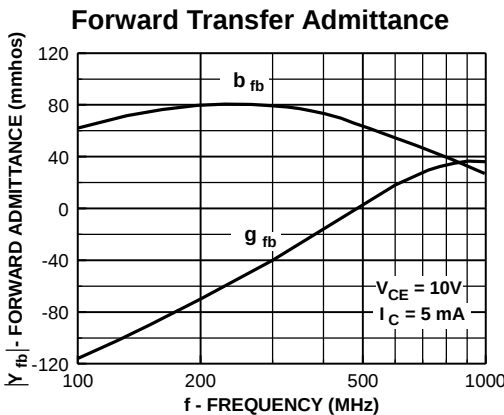
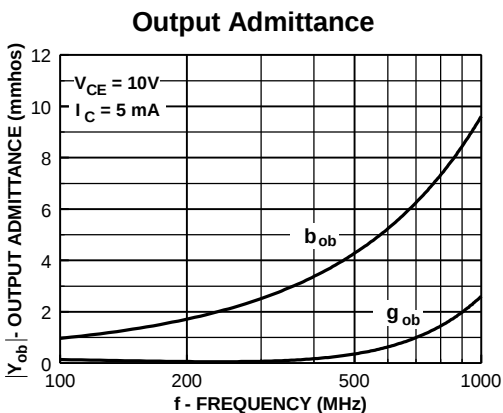
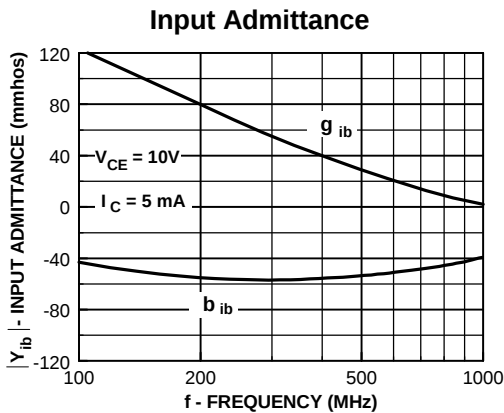


Power Dissipation vs
Ambient Temperature



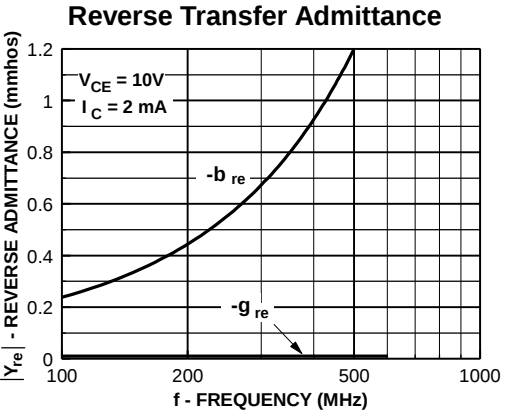
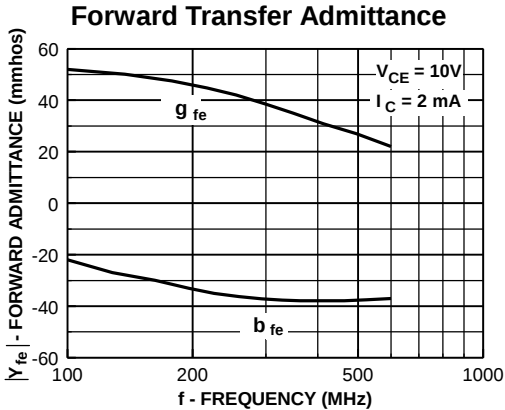
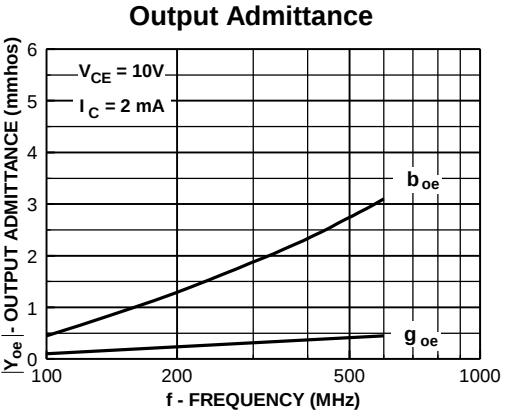
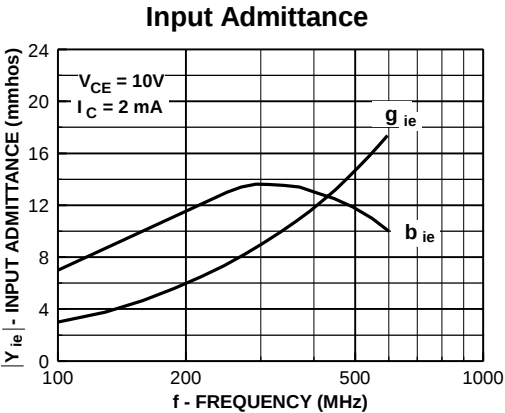
NPN RF Transistor
(continued)

Common Base Y Parameters vs. Frequency



NPN RF Transistor
(continued)

Common Emitter Y Parameters vs. Frequency



NPN RF Transistor (continued)

Test Circuits

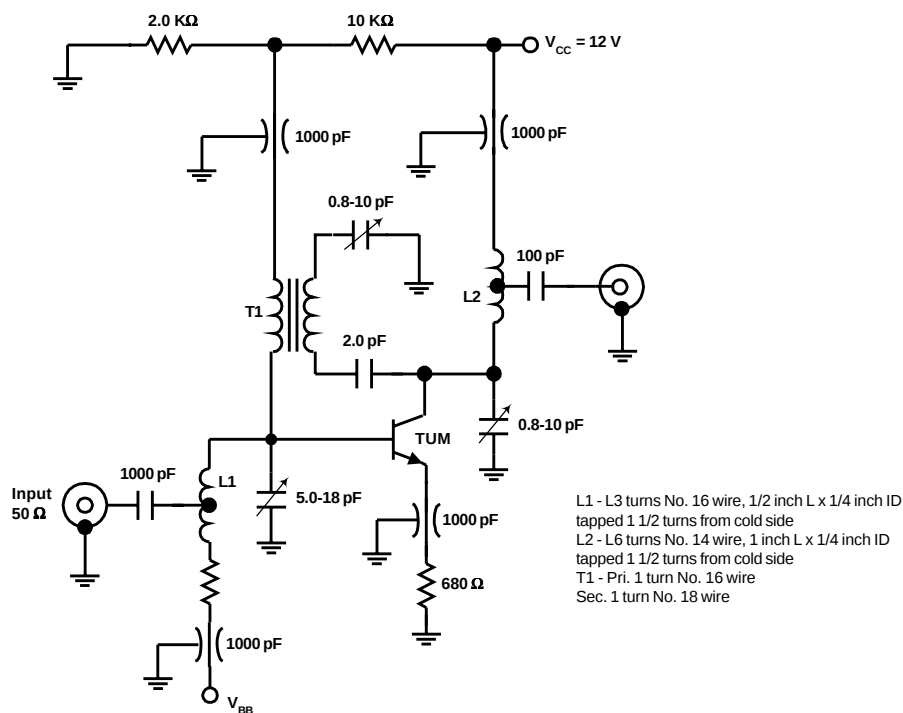


FIGURE 1: Neutralized 200 MHz PG and NF Circuit

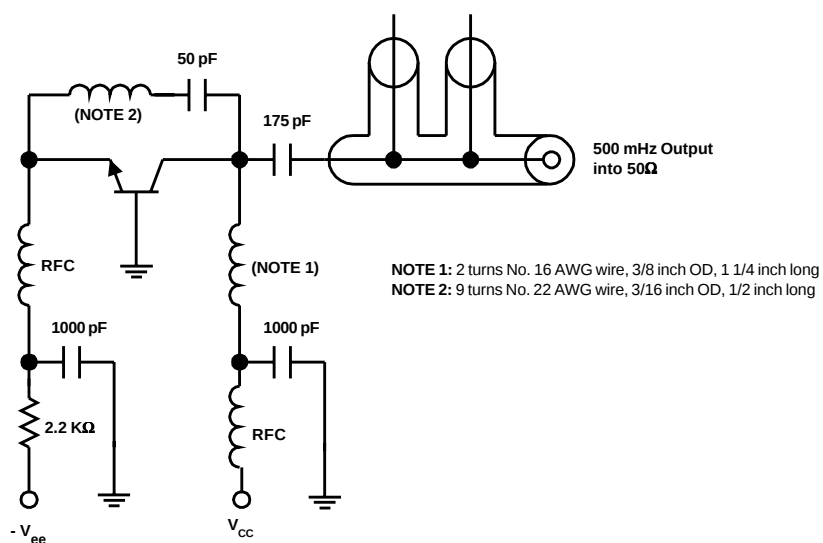


FIGURE 2: 500 MHz Oscillator Circuit

TO-92 Tape and Reel Data

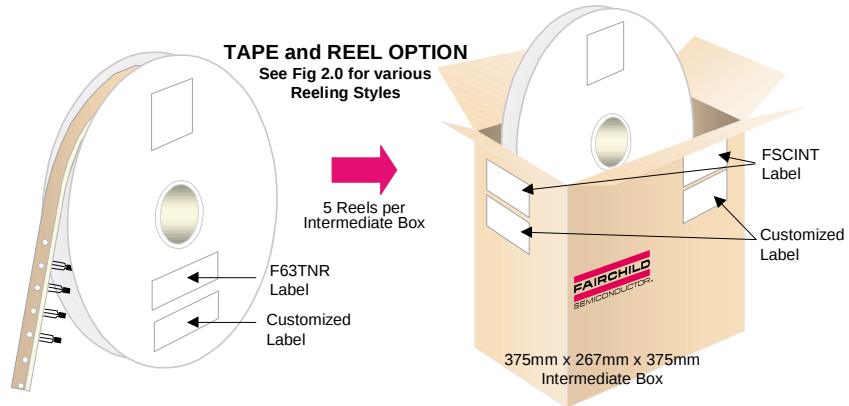


TO-92 Packaging Configuration: Figure 1.0

FSCINT Label sample



F63TNR Label sample



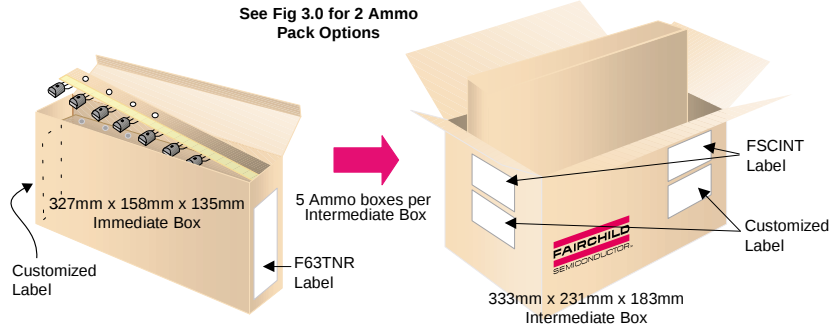
TO-92 TNR/AMMO PACKING INFORMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
 Reel weight with components = 1.04 kg
 Ammo weight with components = 1.02 kg
 Max quantity per intermediate box = 10,000 units

AMMO PACK OPTION

See Fig 3.0 for 2 Ammo Pack Options

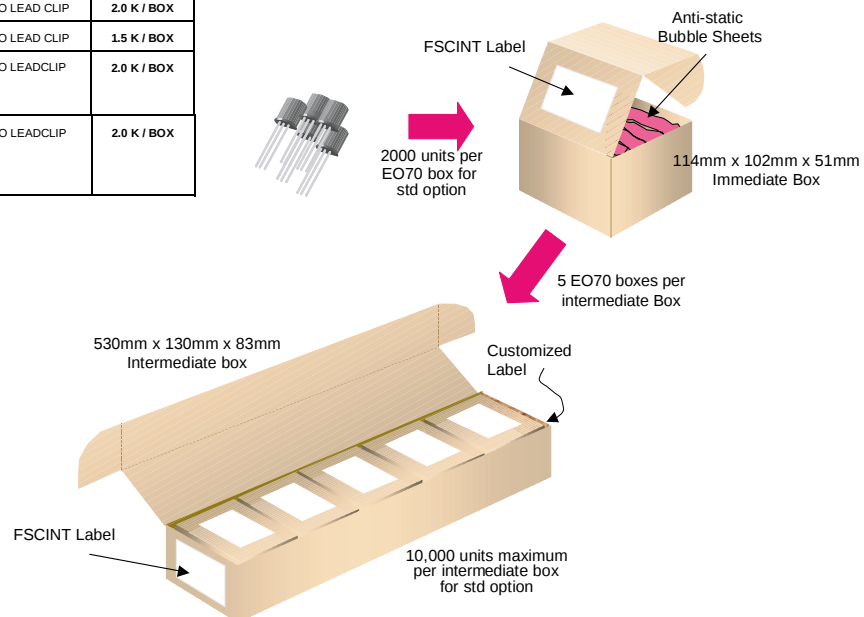


(TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K / BOX
L34Z	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98	NO LEADCLIP	2.0 K / BOX

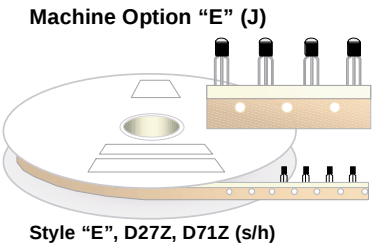
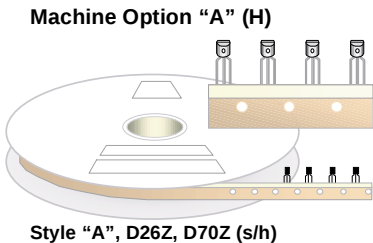
BULK OPTION

See Bulk Packing Information table

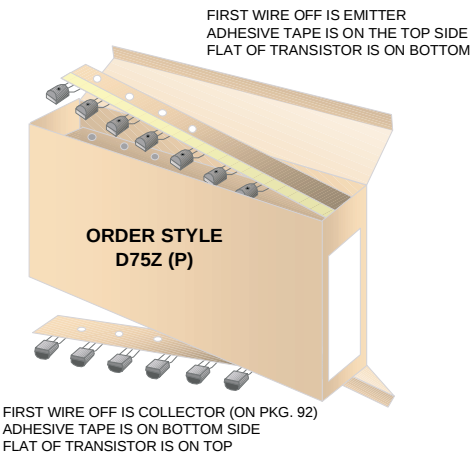
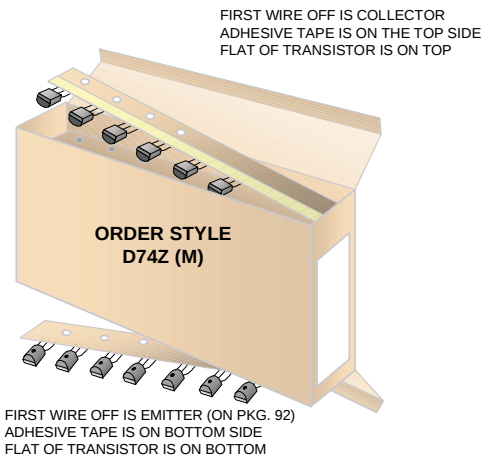


TO-92 Tape and Reel Data, continued

TO-92 Reeling Style Configuration: Figure 2.0

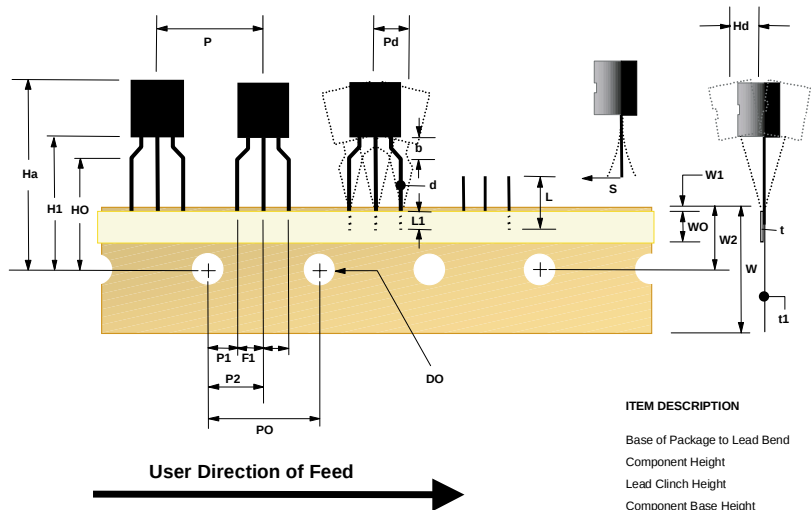


TO-92 Radial Ammo Packaging Configuration: Figure 3.0



TO-92 Tape and Reel Data, continued

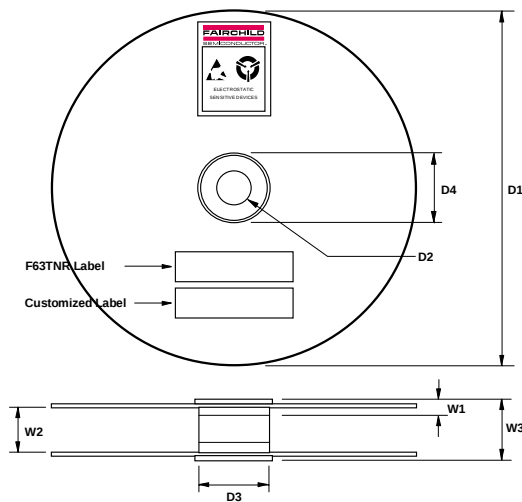
TO-92 Tape and Reel Taping Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

TO-92 Reel Configuration: Figure 5.0



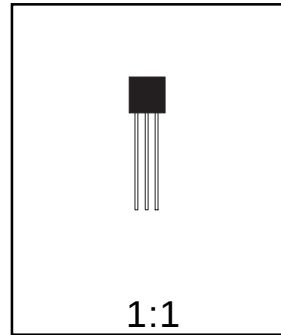
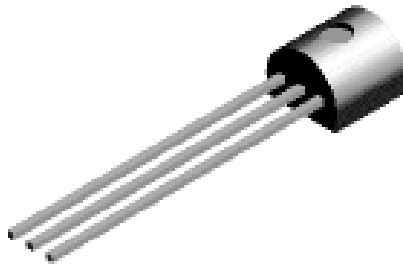
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
Arbor Hole Diameter (Small Hole)	D3	0.650	0.700
Core Diameter	D4	3.100	3.300
Hub Recess Inner Diameter	D5	2.700	3.100
Hub Recess Depth	D6	0.370	0.570
Flange to Flange Inner Width	W1	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

TO-92 Package Dimensions



TO-92 (FS PKG Code 92, 94, 96)



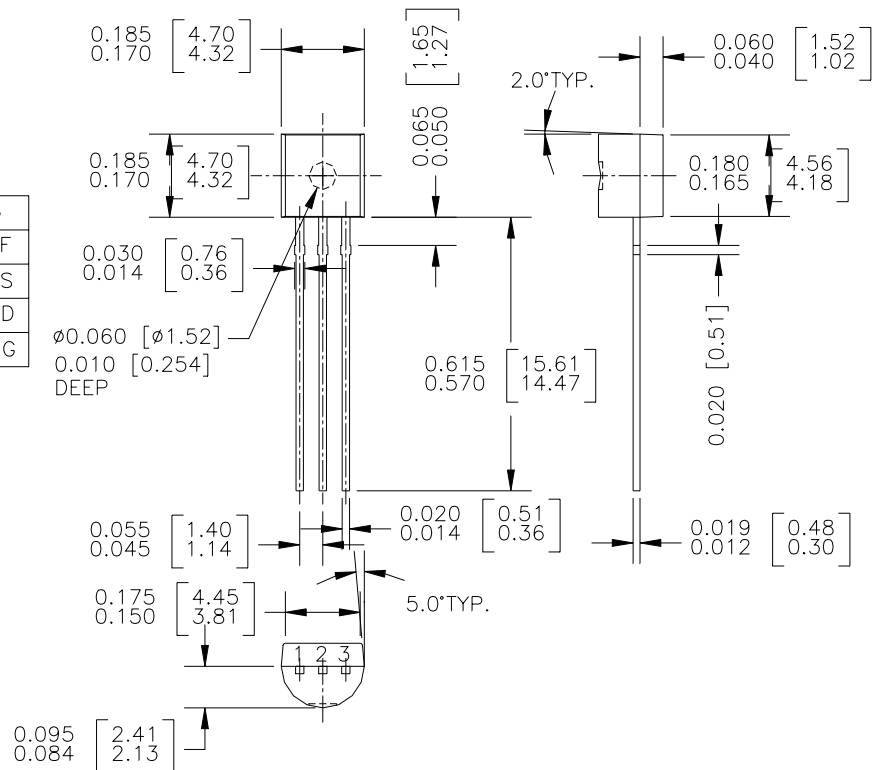
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO-92 (92,94,96)

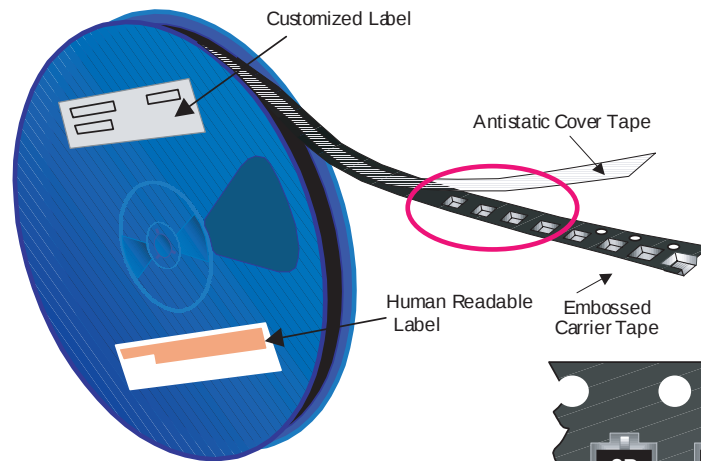
PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G



SOT-23 Tape and Reel Data



SOT-23 Packaging Configuration: Figure 10

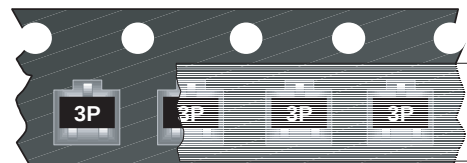


Packaging Description:

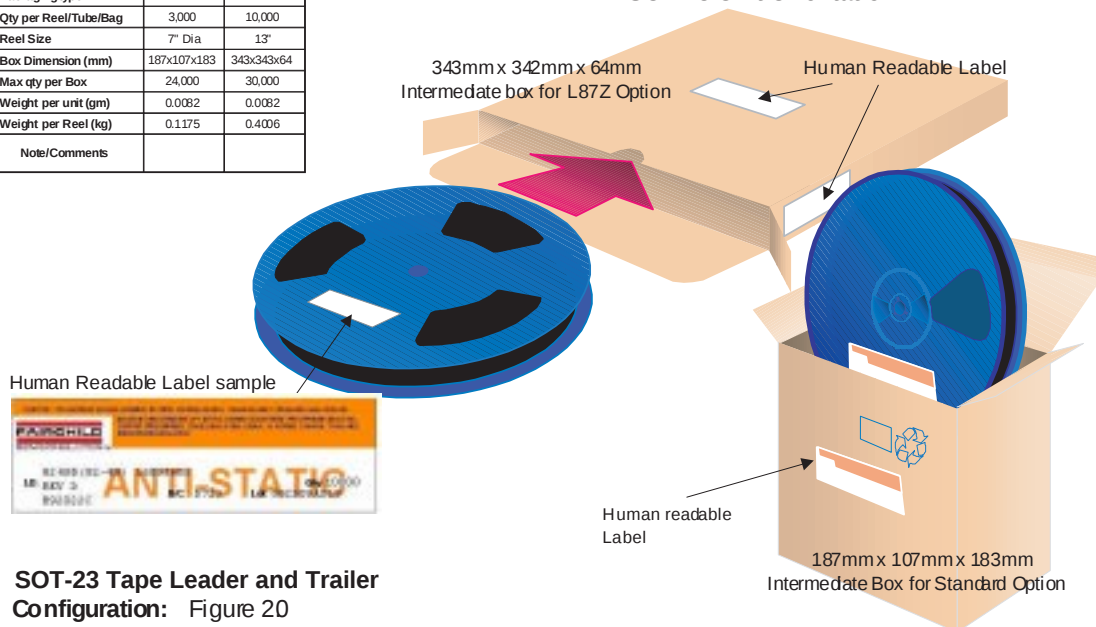
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177mm diameter reel. The reels are dark blue in color and are made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330mm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually labeled and placed inside a standard intermediate made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains eight reels maximum. And these intermediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.

SOT-23 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	187x107x183	343x343x64
Max qty per Box	24,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		



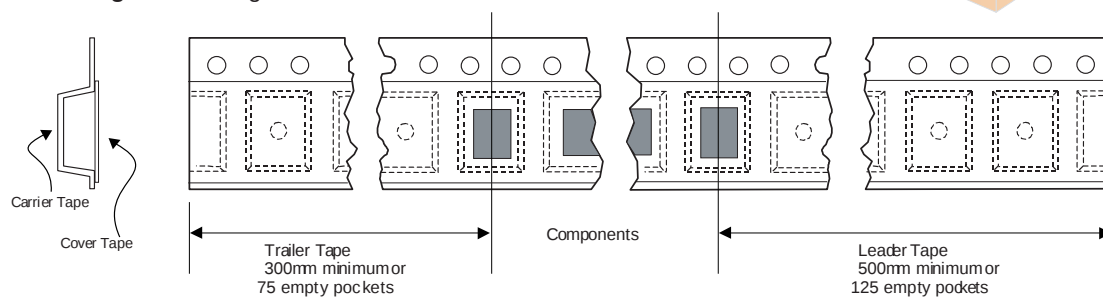
SOT-23 Unit Orientation



Human Readable Label sample



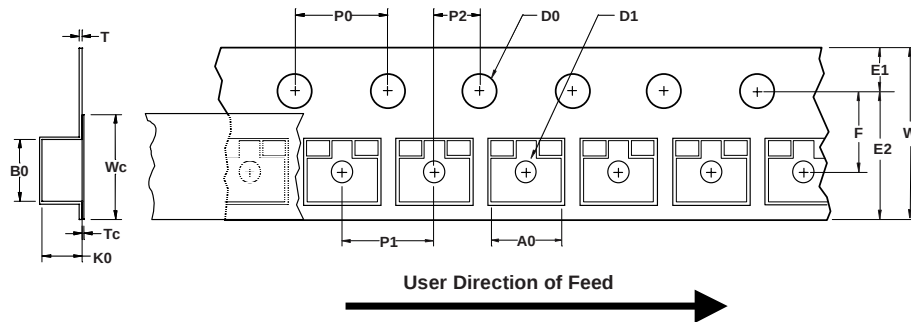
SOT-23 Tape Leader and Trailer Configuration: Figure 20



SOT-23 Tape and Reel Data, continued

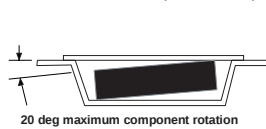
SOT-23 Embossed Carrier Tape

Configuration: Figure 3.0

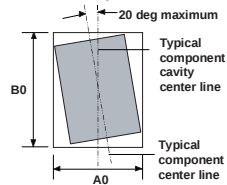


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

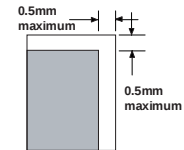
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

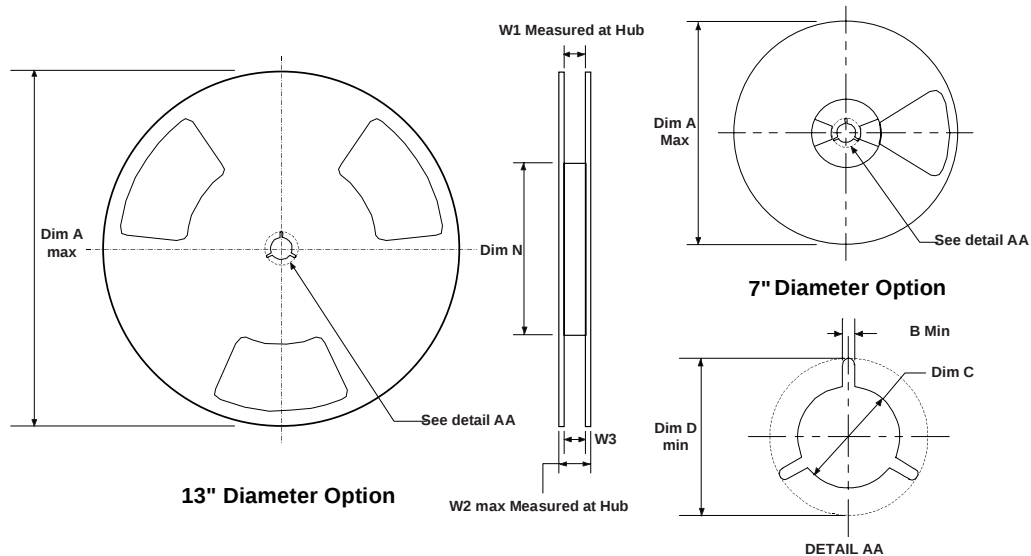


Sketch B (Top View)
Component Rotation



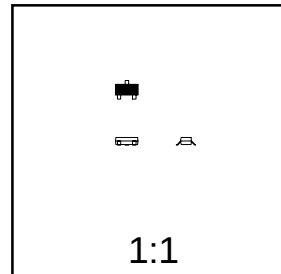
Sketch C (Top View)
Component lateral movement

SOT-23 Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

FAIRCHILD
SEMICONDUCTOR™



Dimensions shown below are in:
inches [millimeters]

The image displays three mechanical drawings of a 3-lead low profile package:

- Top View:** Shows the package with three leads labeled 1, 2, and 3. Dimensions include:
 - Lead 1 width: 0.0910 ± 0.0070 [0.0080]
 - Lead 2 width: 0.0375 ± 0.0025 [0.95 ± 0.06]
 - Lead 3 width: 0.0750 ± 0.0050 [1.91 ± 0.13]
 - Lead 1 to Lead 2 distance: 2.31 ± 0.18 [-0.20]
 - Lead 2 to Lead 3 distance: 0.0510 ± 0.0040 [1.30 ± 0.10]
 - Lead 1 to Lead 3 distance: 0.0240 [0.61]
 - Lead 1 to Lead 2 distance: 0.0160 ± 0.0025 [0.41 ± 0.06] TYP.
 - Lead 2 to Lead 3 distance: 0.0375 ± 0.0025 [0.95 ± 0.06]
 - Lead 1 to Lead 3 distance: 0.0240 [0.61]
 - Lead 1 to Lead 2 distance: 0.0160 ± 0.0025 [0.41 ± 0.06] TYP.
 - Lead 2 to Lead 3 distance: 0.0375 ± 0.0025 [0.95 ± 0.06]
- Side View:** Shows the package profile with dimensions:
 - Lead 1 height: 0.0430 [1.09]
 - Lead 2 height: 0.0350 [0.89]
 - Lead 3 height: 0.1150 ± 0.0050 [2.92 ± 0.13]
 - Lead 1 to Lead 2 distance: 0.0365 [0.93]
 - Lead 2 to Lead 3 distance: 0.0200 ± 0.0040 [-0.0020] [0.51 ± 0.10] TYP.
 - Lead 1 to Lead 3 distance: 0.0040 [0.10] TYP.
- Land Pattern Recommendation:** Shows the recommended land pattern for the package with dimensions:
 - Lead 1 land width: 0.0300 [0.76]
 - Lead 2 land width: 0.0300 [0.76]
 - Lead 3 land width: 0.0375 [0.95]
 - Lead 1 to Lead 2 distance: 0.0900 [2.29]
 - Lead 2 to Lead 3 distance: 0.0375 [0.95]
 - Lead 1 to Lead 3 distance: 0.0300 [0.76]

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

SOT 23, 3 LEADS LOW PROFILE

1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS
MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42

September 1998, Rev. A1

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